

描述 / Descriptions

SOT-23 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-23 Plastic Package.

特征 / Features

P_C 大, h_{FE} 高且特性好, 与 9012M 互补, 无卤产品。

High P_C and h_{FE} , excellent h_{FE} linearity, complementary pair with 9012M, HF Product.

用途 / Applications

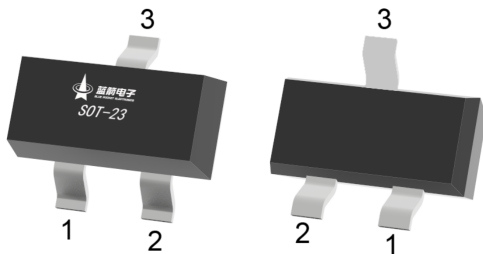
用于收音机推挽功放。

Amplifier of portable radios in class B push-pull operation.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : Base

PIN 2 : Emitter

PIN 3 : Collector

放大及印章代码 / h_{FE} Classifications & Marking

h_{FE} Classifications Symbol	D	E	F	G	H	I
h_{FE} Range	64~91	78~112	96~135	112~166	144~202	188~276
Marking	HJ3D	HJ3E	HJ3F	HJ3G	HJ3H	HJ3I

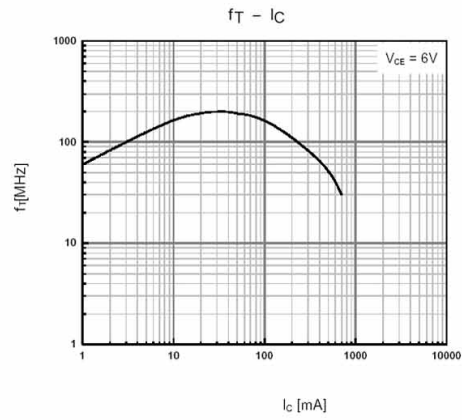
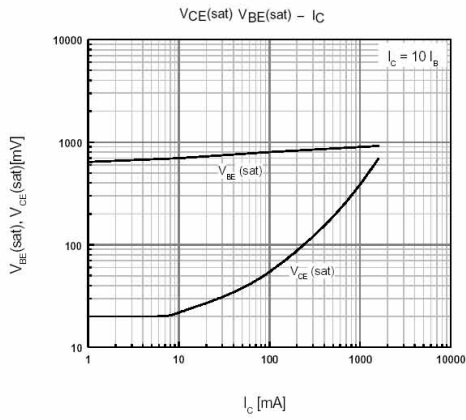
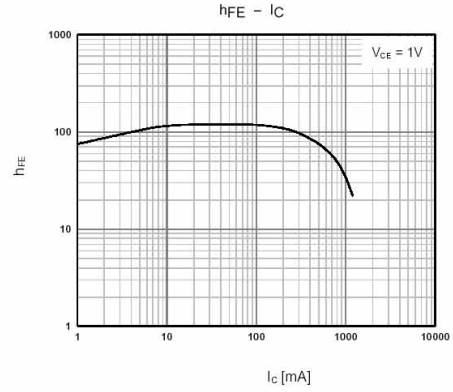
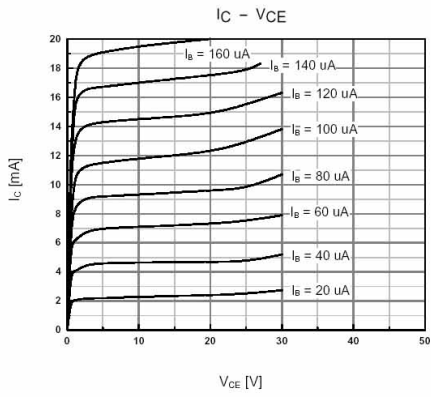
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V _{CBO}	40	V
Collector to Emitter Voltage	V _{CEO}	20	V
Emitter to Base Voltage	V _{EBO}	5.0	V
Collector Current	I _C	500	mA
Base Current	I _B	100	mA
Collector Power Dissipation	P _C	300	mW
Junction Temperature	T _j	150	°C
Storage Temperature Range	T _{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Base Breakdown Voltage	V _{CBO}	I _C =0.1mA I _E =0	40			V
Collector to Emitter Breakdown Voltage	V _{CEO}	I _C =1.0mA I _B =0	20			V
Emitter to Base Breakdown Voltage	V _{EBO}	I _E =0.1mA I _C =0	5.0			V
Collector Cut-Off Current	I _{CBO}	V _{CB} =25V I _E =0			0.1	μA
Emitter Cut-Off Current	I _{EBO}	V _{EB} =3.0V I _C =0			0.1	μA
DC Current Gain	h _{FE(1)}	V _{CE} =1.0V I _C =50mA	150		300	
	h _{FE(2)}	V _{CE} =1.0V I _C =500mA	40			
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C =500mA I _B =50mA		0.16	0.6	V
Base-Emitter saturation Voltage	V _{BE(sat)}	I _C =500mA I _B =50mA		0.91	1.2	V
Base-Emitter Voltage	V _{BE}	V _{CE} =1.0V I _C =10mA		0.67	0.7	V

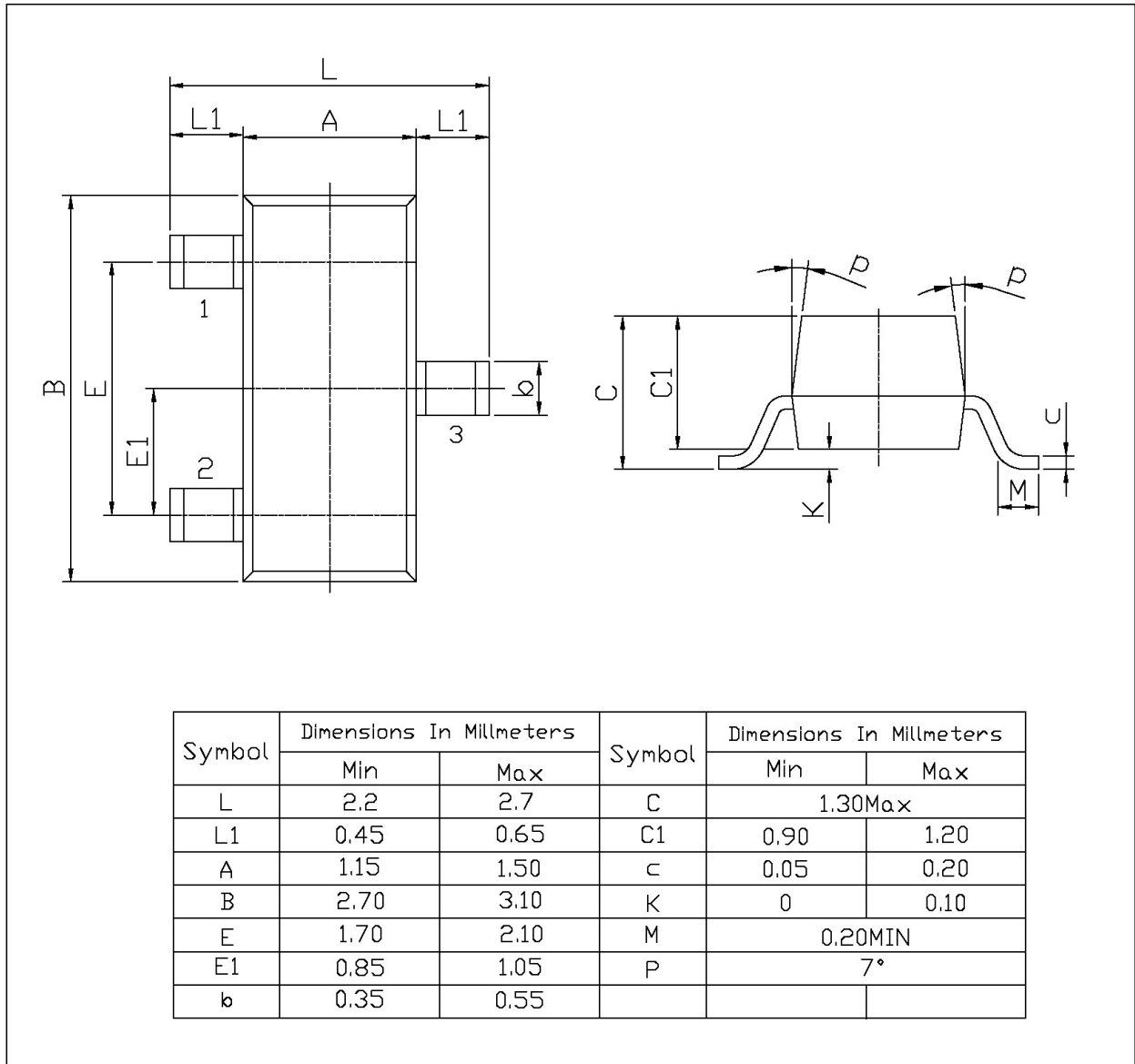
电参数曲线图 / Electrical Characteristic Curve



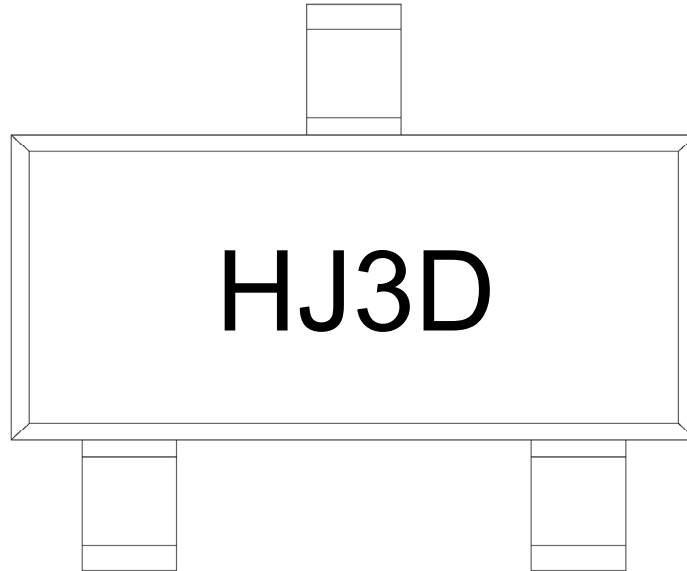
外形尺寸图 / Package Dimensions

SOT-23

单位: mm



印章说明 / Marking Instructions



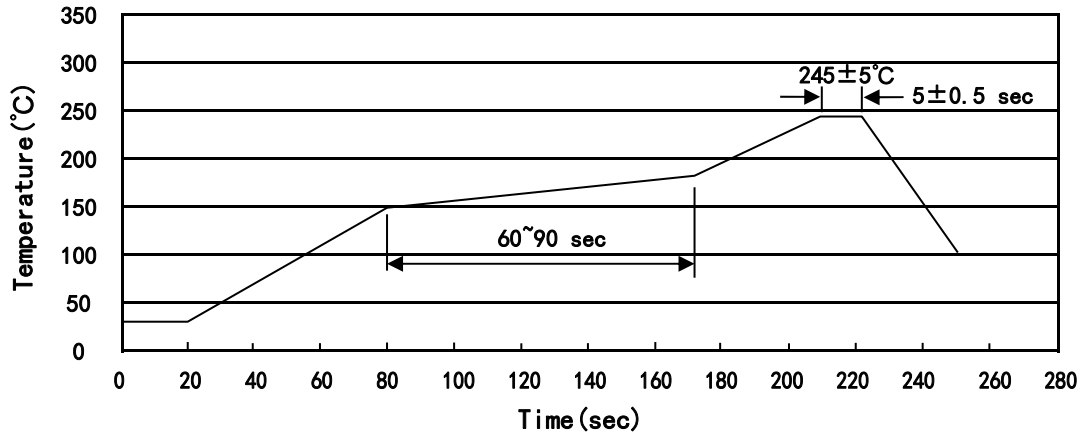
说明：

H： 为公司代码
J3： 为型号代码
D： 为 h_{FE} 档次代码

Note:

H： Company Code
J3： Product Type Code
D： h_{FE} Classifications Symbol Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 150~180°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" ×8	180×120×180	390×385×205

使用说明 / Notices